

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Farameter	Symbol	Emitting Color	Тур.	Max.	Onit
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Super Bright Yellow	590	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Super Bright Yellow	590	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Super Bright Yellow	20	-	nm
Capacitance	С	Super Bright Yellow	20	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Super Bright Yellow	2.0	2.5	V
Reverse Current (V _R = 5V)	I _R	Super Bright Yellow	-	10	μА
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C \leq T \leq 85°C	$TC_{\lambda peak}$	Super Bright Yellow	0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C \leq T \leq 85°C	TC_{\lambdadom}	Super Bright Yellow	0.07	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TC _V	Super Bright Yellow	-1.9	-	mV/°C

Notes:

1. The dominant wavelength (\lambda\rightarrow) above is the setup value of the sorting machine. (Tolerance \lambda : \pm 1nm.)

2. Forward voltage: \pm 2.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	175	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	650	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	480	°C/W

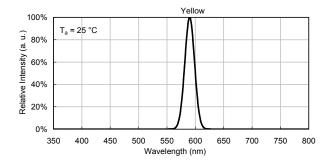
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. $R_{\text{th}, JA}$, $R_{\text{th}, IS}$ Results from mounting on PC board FR4 (pad size \geq 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



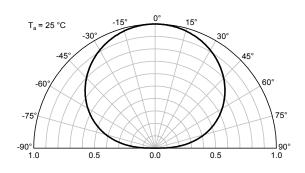


TECHNICAL DATA

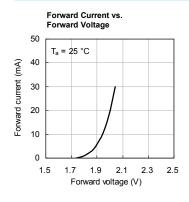
RELATIVE INTENSITY vs. WAVELENGTH

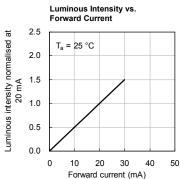


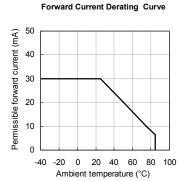
SPATIAL DISTRIBUTION

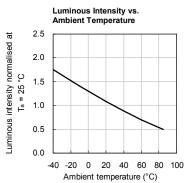


SUPER BRIGHT YELLOW

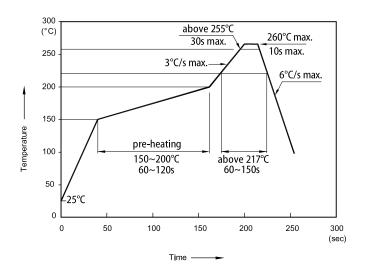








REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



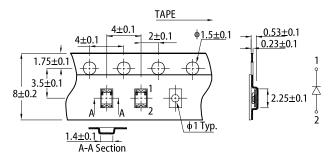
Notes:

- 1. Don't cause stress to the LEDs while it is exposed to high temperature.

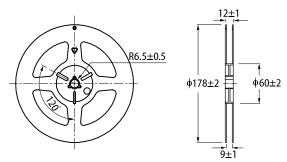
 2. The maximum number of reflow soldering passes is 2 times.

 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units: mm)



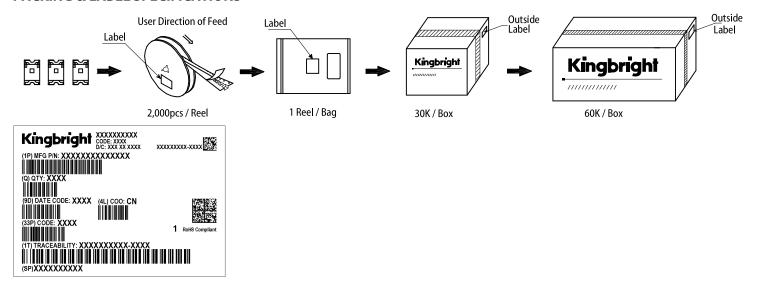
REEL DIMENSION (units:mm)







PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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